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| 10/566,811   | 11/16/2007  | Richard Spitz          | 10191/4496          | 8036             |
| 26646 7590 06/02/2011<br>KENYON & KENYON LLP<br>ONE BROADWAY<br>NEW YORK, NY 10004 |             |                        |                     |                  |
| EXAMINER<br>PHAM, EMILY P  |             |                        |                     |                  |
| ART UNIT<br>2838   |             | PAPER NUMBER           |                     |                  |
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**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.

# Office Action Summary

**Application No.**

10/566,811

**Applicant(s)**

SPITZ ET AL.

**Examiner**

Emily Pham

**Art Unit**

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**Period for Reply** -- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☒ Responsive to communication(s) filed on 18 January 2011.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 9, 11, 13, 15, 17 and 19-30 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 9, 11, 13, 15, 17 and 19-30 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 15 January 2010 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.
- Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

**Priority under 35 U.S.C. § 119**

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All b) ☐ Some \* c) ☐ None of:
- 1) ☒ Certified copies of the priority documents have been received.
  - 2) ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  - 3) ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

**Attachment(s)**

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-946)
- 3) ☐ Information Disclosure Statement(s) (PTO/SB/08)  
Paper No(s)/Mail Date \_\_\_\_\_
- 4) ☐ Interview Summary (PTO-413)  
Paper No(s)/Mail Date \_\_\_\_\_
- 5) ☐ Notice of Informal Patent Application
- 6) ☐ Other: \_\_\_\_\_

### DETAILED ACTION

1. This Office Action is in response to the Amendment filed on 01/18/2011.

Examiner's Note:

The following limitations of claim 9 make it a product by process claim: a) "a nickel layered wire contact attached to the diode chip at a temperature greater than a silver-solder alloy melting point", and b) "only a section of the nickel layered wire contact remaining unexposed to solder during manufacturing of the press-fit diode is plated with silver".

The following limitations of claims 19, 21, 22, 23, and 29 make them a product by process claim: a) "the silver layer is applied before the press-fit diode is assembled"; b) "the wire contact is inserted in a rack with a wire shaft pointing downward, and wherein the wire shaft is immersed in an electroplating vat" ; c) "a central section of the press-fit diode is sheathed in plastic to protect the diode chip"; d) "press-fit diode is electroplated in bulk in a drum process"; and e) "wherein the silver layer is applied before the press-fit diode is assembled, wherein a region for attaching the diode chip is recessed, wherein the wire contact is inserted in a rack with a wire shaft pointing downward, wherein the wire shaft is immersed in an electroplating vat, wherein a central section of the press-fit diode is sheathed in plastic to protect the diode chip, and wherein the press-fit diode is electroplated in bulk in a drum process".

The MPEP § 2113, states, "Even though product -by[-] process claims are limited by and defined by the process, determination of patentability is based upon the product itself. The patentability of a product does not depend on its

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method of production. If the product in product-by-process claim is the same as or obvious from a product of the prior art, the claim is unpatentable even though the prior product is made by a different process." *In re Thorpe*, 227 USPQ 964, 966 (Fed. Cir. 1985)(citations omitted).

A "product by process" claim is directed to the product per se, no matter how actually made, *In re Hirao and Sato et al.*, 190 USPQ 15 at 17 (CCPA 1976) (footnote 3). See also *In re Brown and Saffer*, 173 USPQ 685 (CCPA 1972); *In re Luck and Gainer*, 177 USPQ 523 (CCPA 1973); *In re Fessmann*, 180 USPQ 324 (CCPA 1974); and *In re Marosi et al.*, 218 USPQ 289 (CAFC 1983) final product per se which must be determined in a "product by, all of" claim, and not the patentability of the process, and that an old or obvious product, whether claimed in "product by process" claims or not. Note that Applicant has the burden of proof in such cases, as the above case law makes clear.

### ***Claim Objections***

2. Claim 11 is objected to because claim 11 is dependent on canceled claim
10. Appropriate correction is required.

### ***Claim Rejections - 35 USC § 112***

3. The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

4. Claims 9 and 13 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to

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reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. Claim 9 recites the limitation "a nickel layered wire contact attached to the diode chip at a temperature greater than a silver-solder alloy melting point to form a second terminal of the press-fit diode" in lines 5-6, claim 13 recites the limitation "fixedly connecting the wire head and base contact to the diode chip at a wire head temperature exceeding a melting point of a silver-solder alloy, contact, the base contact, and the diode chip to one another" in lines 14-15. Paragraph [0011] of Specification discusses the melting point of good soldering such as silver but does not disclose the wire is attached to the diode chip at a temperature greater/exceeds a melting point of a silver-solder alloy.

***Claim Rejections - 35 USC § 103***

5. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

6. Claims 9, 11, 20, 22, and 23 are rejected under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of Hayakawa (JP 03064053), and further in view of Shiga et al (JP 61124597).

Regarding independent claim 9: AAPA (For example: see FIG 1, par [0003] – par [0006]) discloses a press-fit diode (1), comprising a diode chip (7); a base contact (3) for pressing the press-fit diode (1) into a substrate, wherein

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the base contact (3) is attached to the diode chip (7) and forms a first terminal of the press-fit diode (1); and a wire contact (2, 4) which forms a second terminal of the press-fit diode (1).

AAPA fails to disclose a nickel layered wire contact attached to the diode chip at a temperature greater than a silver-solder alloy melting point.

However, Hayakawa (**For example: see translation of Abstract**) teaches a nickel layered wire contact (**Ni plating layer**) attached to the diode chip (**other layer at lead junction**) at a temperature greater than a silver-solder alloy melting point (**the two-layer plating layer is fused by heating at Ag-Cu alloy eutectic temperature or more**). It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include "a nickel layered wire contact attached to the diode chip at a temperature greater than a silver-solder alloy melting point" by Hayakawa, for the purpose of improving junction strength (**Purpose of Abstract**).

Additionally, since AAPA and Hayakawa are from the same field of endeavor (**soldering**), the purpose taught by Hayakawa would have been recognized in the pertinent arts of AAPA.

Furthermore, AAPA fails to disclose only a section of the nickel layered wire contact remaining unexposed to solder during manufacturing of the press-fit diode is plated with silver.

However, Shiga et al (**For example: see translation of Abstract**) teaches only a section of the nickel layered wire contact (**surface layer 2 is**

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**formed of Ni**) remaining unexposed to solder during manufacturing of the press-fit diode is plated with silver (**coating partially Ag on a base material having Ni surface layer**). It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include "only a section of the nickel layered wire contact remaining unexposed to solder during manufacturing of the press-fit diode is plated with silver" by Shiga et al, for the purpose of maintaining the electrical connecting characteristic of an electric material over a long period of time (**Purpose of Abstract**).

Additionally, since AAPA and Shiga et al are from the same field of endeavor (**soldering**), the purpose taught by Shiga et al would have been recognized in the pertinent arts of AAPA.

Regarding claim 11: AAPA (**For example: see FIG 1**) discloses the base contact is not provided with a silver layer.

Regarding claims 20: AAPA (**For example: see FIG 1, paragraph [0003]**) discloses the press-fit diode as recited in claim 9, wherein a region for attaching the diode chip is recessed.

Regarding claims 22: AAPA (**For example: see FIG 1**) discloses a central section of the press-fit diode is sheathed in plastic (**9; For example: see par [0006]**) to protect the diode chip.

Regarding claims 23: AAPA (**For example: see par [0007]**) discloses the press-fit diode is electroplated in bulk in a drum process (**electroplated in bulk in a drum tin plating process**).

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7. Claims 13, 15, 25-28, and 30 are rejected under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of Wang et al (USP 7,361,257) in view of Shiga et al (JP 61124597) and further in view of Hayakawa (JP 03064053).

Regarding independent claim 13: AAPA (**For example: see FIG 1, par [0003] – par [0006]**) discloses a method for manufacturing a press-fit diode, comprising: providing a diode chip; providing a base contact configured for pressing the press-fit diode into a substrate, wherein the base contact forms a first terminal of the press-fit diode; providing a nickel layered wire contact having a wire head and a wire shaft which forms a second terminal of the press-fit diode.

First, AAPA fails to disclose immersing the wire shaft of the wire contact in an electroplating vat to silver plate the wire shaft.

However, Wang et al (**For example: see FIG 13, lines 52-53 of col. 14**) teaches immersing the wire shaft of the wire contact in an electroplating vat to silver plate the wire shaft. It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include "immersing the wire shaft of the wire contact in an electroplating vat to silver plate the wire shaft" by Wang et al for the purpose of effectively coating the wire shaft.

Additionally, since AAPA and Wang et al are from the same field of endeavor (press-fit), the purpose taught by Wang et al would have been recognized in the pertinent arts of AAPA.



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Second, AAPA fails to disclose to silver plate only a section of the nickel layered wire shaft remaining unexposed to solder during manufacturing of the press-fit diode.

However, Shiga et al (**For example: see translation of Abstract**) teaches to silver plate only a section (**coating partially Ag on a base material having Ni surface layer**) of the nickel layered wire shaft (**surface layer 2 is formed of Ni**) remaining unexposed (**coating partially Ag on a base material having Ni surface layer**) to solder during manufacturing of the press-fit diode. It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include "to silver plate only a section of the nickel layered wire shaft remaining unexposed to solder during manufacturing of the press-fit diode" by Shiga et al, for the purpose of maintaining the electrical connecting characteristic of an electric material over a long period of time (**Purpose of Abstract**).

Additionally, since AAPA and Shiga et al are from the same field of endeavor (**soldering**), the purpose taught by Shiga et al would have been recognized in the pertinent arts of AAPA.

Third, AAPA fails to disclose fixedly connecting the wire head and base contact to the diode chip at a wire head temperature exceeding a melting point of a silver-solder alloy.

However, Hayakawa (**For example: see translation of Abstract**) teaches fixedly connecting the wire head and base contact (**Ni plating layer**) to the diode chip (**other layer at lead junction**) at a wire head temperature

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exceeding a melting point of a silver-solder alloy (**the two-layer plating layer is fused by heating at Ag-Cu alloy eutectic temperature or more**). It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include “fixedly connecting the wire head and base contact to the diode chip at a wire head temperature exceeding a melting point of a silver-solder alloy” by Hayakawa, for the purpose of improving junction strength (**Purpose of Abstract**).

Additionally, since AAPA and Hayakawa are from the same field of endeavor (**soldering**), the purpose taught by Hayakawa would have been recognized in the pertinent arts of AAPA.

Regarding claim 15: AAPA (**For example: see FIG 1**) discloses the base contact is not provided with a silver layer.

Regarding claim 25: AAPA (**For example: see FIG 1, paragraph [0003]**) discloses the press-fit diode as recited in claim 9, wherein a region for attaching the diode chip is recessed.

Regarding claim 26: AAPA fails to disclose the wire contact is inserted in a rack with a wire shaft pointing downward, and wherein the wire shaft is immersed in an electroplating vat.

However, Wang et al (**For example: see FIG 13, lines 52-53 of col. 14**) teaches the wire contact (**electrode**) is inserted in a rack (**170**) with a wire shaft (**shaft of electrode**) pointing downward, and wherein the wire shaft (**shaft of electrode**) is immersed (**For example: see line 19 of col. 17: partially immersed**) in an electroplating vat (**electrolyte bath**). It would have been

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obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include the wire contact inserted in a rack with a wire shaft pointing downward and the wire shaft immersed in an electroplating vat by Wang et al for the purpose of effectively coating the wire shaft.

Additionally, since AAPA and Wang et al are from the same field of endeavor, the purpose taught by Wang et al would have been recognized in the pertinent arts of AAPA.

Regarding claim 27: AAPA (**For example: see FIG 1**) discloses a central section of the press-fit diode is sheathed in plastic (**9; For example: see par [0006]**) to protect the diode chip.

Regarding claim 28: AAPA (**For example: see par [0007]**) discloses the press-fit diode is electroplated in bulk in a drum process (**electroplated in bulk in a drum tin plating process**).

Regarding claim 30: AAPA (**For example: see FIG 1**) discloses a region for attaching the diode chip is recessed, sheathing (**9**) a central section of the press-fit diode to protect the diode chip (**7**); wherein the press-fit diode (**1**) is electroplated in bulk in a drum process (**For example: see par [0007], electroplated in bulk in a drum tin plating process**).

AAPA fails to disclose inserting the wire contact in a rack with a wire shaft pointing downward; immersing the wire shaft in an electroplating vat.

However, Wang et al (**For example: see FIG 13, lines 52-53 of col. 14**) teaches inserting the wire contact (**electrode**) in a rack (**170**) with a wire shaft

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(**shaft of electrode**) pointing downward; immersing the wire shaft (**shaft of electrode**) in an electroplating vat (**electrolyte bath**). It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include inserting the wire contact in a rack with a wire shaft pointing downward; immersing the wire shaft in an electroplating vat by Wang et al for the purpose of effectively coating the wire shaft.

Additionally, since AAPA and Wang et al are from the same field of endeavor, the purpose taught by Wang et al would have been recognized in the pertinent arts of AAPA.

8. Claims 17 and 24 are rejected under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of Wang et al (USP 7,361,257) in view of Shiga et al (JP 61124597) in view of Hayakawa (JP 03064053) and further in view of Dibugnara (USP 3,844,029).

Regarding claim 17: AAPA (**For example: see FIG 1, paragraph [0006]**) discloses the wire contact is made of copper, and the wire contact is further provided with a nickel layer

AAPA fails to disclose the silver layer is applied on a nickel layer.

However, Dibugnara (**For example: see lines 30-32 of col. 10**) teaches the silver layer (**silver layer**) is applied on a nickel layer (**nickel layer**). It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include the wire

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contact with a silver layer applied on a nickel layer by Dibugnara for the purpose of providing necessary soldering characteristics.

Additionally, since AAPA and Dibugnara are from the same field of endeavor, the purpose taught by Dibugnara would have been recognized in the pertinent arts of AAPA.

Regarding claim 24: AAPA fails to disclose the silver layer is applied before the press-fit diode is assembled.

However, Dibugnara (**For example: see FIG 7, FIG 9**) teaches the silver layer (**38a**) is applied before the press-fit diode (**diode**) is assembled (**FIG 9**). It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include the silver layer applied before the press-fit diode is assembled by Dibugnara for the purpose of properly coating the wire.

Additionally, since AAPA and Dibugnara are from the same field of endeavor, the purpose taught by Dibugnara would have been recognized in the pertinent arts of AAPA.

9. Claim 19 is rejected under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of Hayakawa (JP 03064053) in view of Shiga et al (JP 61124597) and further in view of Dibugnara (USP 3,844,029).

Regarding claim 19: AAPA fails to disclose the silver layer is applied before the press-fit diode is assembled.

However, Dibugnara (**For example: see FIG 7, FIG 9**) teaches the silver layer (**38a**) is applied before the press-fit diode (**diode**) is assembled (**FIG 9**). It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include the silver layer applied before the press-fit diode is assembled by Dibugnara for the purpose of properly coating the wire.

Additionally, since AAPA and Dibugnara are from the same field of endeavor, the purpose taught by Dibugnara would have been recognized in the pertinent arts of AAPA.

10. Claim 21 is rejected under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of Hayakawa (JP 03064053) in view of Shiga et al (JP 61124597), and further in view of Wang et al (USP 7,361,257).

Regarding claim 21: AAPA fails to disclose the wire contact is inserted in a rack with a wire shaft pointing downward, and wherein the wire shaft is immersed in an electroplating vat.

However, Wang et al (**For example: see FIG 13, lines 52-53 of col. 14**) teaches the wire contact (**electrode**) is inserted in a rack (**170**) with a wire shaft (**shaft of electrode**) pointing downward, and wherein the wire shaft (**shaft of electrode**) is immersed (**For example: see line 19 of col. 17: partially immersed**) in an electroplating vat (**electrolyte bath**). It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include the wire contact inserted in

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a rack with a wire shaft pointing downward and the wire shaft immersed in an electroplating vat by Wang et al for the purpose of effectively coating the wire shaft.

Additionally, since AAPA and Wang et al are from the same field of endeavor, the purpose taught by Wang et al would have been recognized in the pertinent arts of AAPA.

11. Claim 29 is rejected under 35 U.S.C. 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of Hayakawa (JP 03064053) in view of Shiga et al (JP 61124597) in view of Dibugnara (USP 3,844,029) and further in view of Wang et al (USP 7,361,257).

Regarding claim 29: AAPA (**For example: see FIG 1**) discloses a region for attaching the diode chip is recessed, a central section of the press-fit diode (1) is sheathed in plastic (9) to protect the diode chip (7), and the press-fit diode (1) is electroplated in bulk in a drum process (**For example: see par [0007], electroplated in bulk in a drum tin plating process**).

AAPA fails to disclose the silver layer is applied before the press-fit diode is assembled.

However, Dibugnara (**For example: see FIG 7, FIG 9**) teaches the silver layer (38a) is applied before the press-fit diode (diode) is assembled (FIG 9). It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include the silver layer applied before the press-fit diode is assembled by Dibugnara for the purpose of properly coating the wire.

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Additionally, since AAPA and Dibugnara are from the same field of endeavor, the purpose taught by Dibugnara would have been recognized in the pertinent arts of AAPA.

Furthermore, AAPA fails to disclose the wire contact is inserted in a rack with a wire shaft pointing downward, wherein the wire shaft is immersed in an electroplating vat.

However, Wang et al (**For example: see FIG 13, lines 52-53 of col. 14**) teaches the wire contact (**electrode**) is inserted in a rack (**170**) with a wire shaft (**shaft of electrode**) pointing downward, wherein the wire shaft is immersed in an electroplating vat (**electrolyte bath**). It would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the press-fit diode of AAPA to include inserting the wire contact in a rack with a wire shaft pointing downward; immersing the wire shaft in an electroplating vat by Wang et al for the purpose of effectively coating the wire shaft.

Additionally, since AAPA and Wang et al are from the same field of endeavor, the purpose taught by Wang et al would have been recognized in the pertinent arts of AAPA.

### ***Response to Arguments***

12. Applicant's arguments with respect to claims 9 and 13 have been considered but are moot in view of the new ground(s) of rejection.

### ***Conclusion***

13. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**.



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See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

#### ***Contact Information***

14. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Emily Pham whose telephone number is (571)270-3046. The examiner can normally be reached on Mon-Thu (7:00AM - 6:00PM).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Monica Lewis can be reached on (571) 272 - 1838. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/GARY L LAXTON/  
Primary Examiner, Art Unit 2838

May 21, 2011

/EP/